

Title (en)
HEAT SINK FOR AN ELECTRONIC HOUSING

Title (de)
KÜHLKÖRPER FÜR ELEKTRONIKGEHÄUSE

Title (fr)
DISSIPATEUR DE CHALEUR POUR BOÎTIER ÉLECTRONIQUE

Publication
EP 1922177 A1 20080521 (DE)

Application
EP 06777993 A 20060726

Priority
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• DE 102005043055 A 20050909

Abstract (en)
[origin: DE102005043055B3] Production of a cooling body with cooling fins, for an electronics housing, involves (a) preparing extruded profiled slabs (13) with mutually parallel cooling fins, (b) mutually orienting the slabs to give a surface with parallel cooling fins and (c) cutting the slabs to length, using a profiled circular saw (14) with a stepped profile, to give the cooling bodies.

IPC 8 full level
B23P 13/04 (2006.01); **B23P 15/26** (2006.01); **H01L 21/48** (2006.01); **F28F 3/04** (2006.01); **H01L 23/367** (2006.01)

CPC (source: EP US)
B23P 13/04 (2013.01 - EP US); **B23P 15/26** (2013.01 - EP US); **F28F 1/16** (2013.01 - EP US); **H01L 21/4878** (2013.01 - EP US); **H01L 23/367** (2013.01 - EP US); **B23P 2700/10** (2013.01 - EP US); **H01L 2924/0002** (2013.01 - EP US); **Y10T 29/4935** (2015.01 - EP US)

Citation (search report)
See references of WO 2007028672A1

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